



TSM2301

20V P-Channel Enhancement Mode MOSFET

SOT-23



Pin assignment:

1. Gate
2. Source
3. Drain

$$V_{DS} = -20V$$

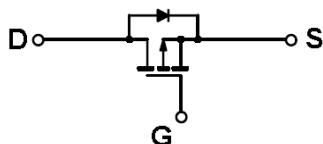
$$R_{DS(on)}, V_{GS} @ -4.5V, I_{DS} @ -2.8A = 130m\Omega$$

$$R_{DS(on)}, V_{GS} @ -2.5V, I_{DS} @ -2.0A = 190m\Omega$$

Features

- ◊ Advanced trench process technology
- ◊ High density cell design for ultra low on-resistance
- ◊ Excellent thermal and electrical capabilities
- ◊ Compact and low profile SOT-23 package

Block Diagram



Ordering Information

Part No.	Packing	Package
TSM2301CX	Tape & Reel	SOT-23

Absolute Maximum Rating ($T_a = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-20V	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Drain Current	I_D	-2.3	A
Pulsed Drain Current	I_{DM}	-10	A
Maximum Power Dissipation	$T_a = 25^\circ C$	P_D	1.25
	$T_a = 75^\circ C$		0.8
Operating Junction Temperature	T_J	+150	$^\circ C$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ C$

Thermal Performance

Parameter	Symbol	Limit	Unit
Lead Temperature (1/8" from case)	T_L	5	S
Junction to Ambient Thermal Resistance (PCB mounted)	$R_{\theta ja}$	100	$^\circ C/W$

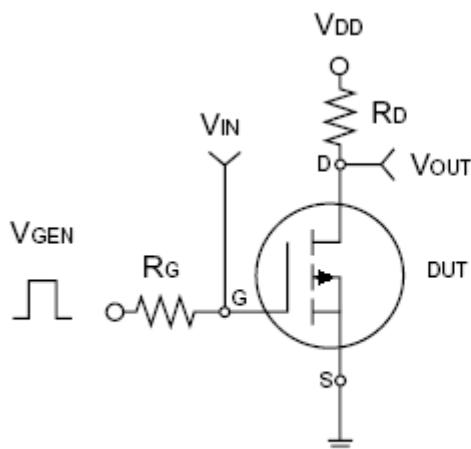
Note: Surface mounted on FR4 board $t \leq 5\text{sec}$.

Electrical Characteristics

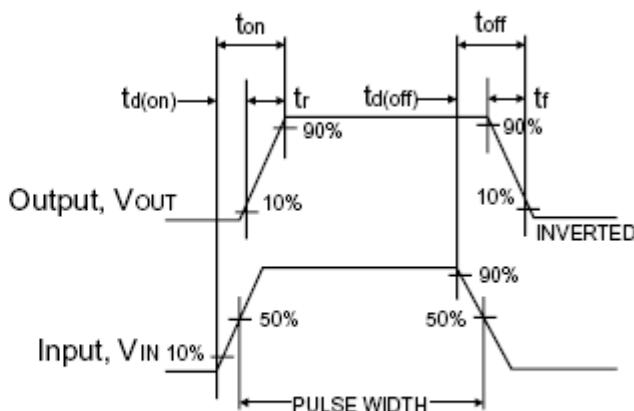
T_a = 25 °C, unless otherwise noted

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = - 250uA	BV _{DSS}	- 20	--	--	V
Drain-Source On-State Resistance	V _{GS} = - 4.5V, I _D = - 2.8A	R _{DS(ON)}	--	95	130	mΩ
Drain-Source On-State Resistance	V _{GS} = - 2.5V, I _D = - 2.0A	R _{DS(ON)}	--	122	190	
Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = - 250uA	V _{GS(TH)}	- 0.45	--	--	V
Zero Gate Voltage Drain Current	V _{DS} = - 16V, V _{GS} = 0V	I _{DSS}	--	--	- 1.0	uA
Gate Body Leakage	V _{GS} = ± 8V, V _{DS} = 0V	I _{GSS}	--	--	± 100	nA
On-State Drain Current	V _{DS} ≥ - 10V, V _{GS} = - 5V	I _{D(ON)}	- 6	--	--	A
Forward Transconductance	V _{DS} = - 5V, I _D = - 2.8A	g _{fs}	--	6.5	--	S
Dynamic						
Total Gate Charge	V _{DS} = - 6V, I _D = - 2.8A, V _{GS} = - 4.5V	Q _g	--	5.4	10	nC
Gate-Source Charge		Q _{gs}	--	0.8	--	
Gate-Drain Charge		Q _{gd}	--	1.1	--	
Turn-On Delay Time	V _{DD} = - 6V, R _L = 6Ω, I _D = - 1A, V _{GEN} = - 4.5V, R _G = 6Ω	t _{d(on)}	--	5	25	nS
Turn-On Rise Time		t _r	--	19	60	
Turn-Off Delay Time		t _{d(off)}	--	95	110	
Turn-Off Fall Time		t _f	--	65	80	
Input Capacitance	V _{DS} = - 6V, V _{GS} = 0V, f = 1.0MHz	C _{iss}	--	447	--	pF
Output Capacitance		C _{oss}	--	127	--	
Reverse Transfer Capacitance		C _{rss}	--	80	--	
Source-Drain Diode						
Max. Diode Forward Current		I _S	--	--	- 1.6	A
Diode Forward Voltage	I _S = - 1.6A, V _{GS} = 0V	V _{SD}	--	- 0.8	- 1.2	V

Note : pulse test: pulse width <=300uS, duty cycle <=2%

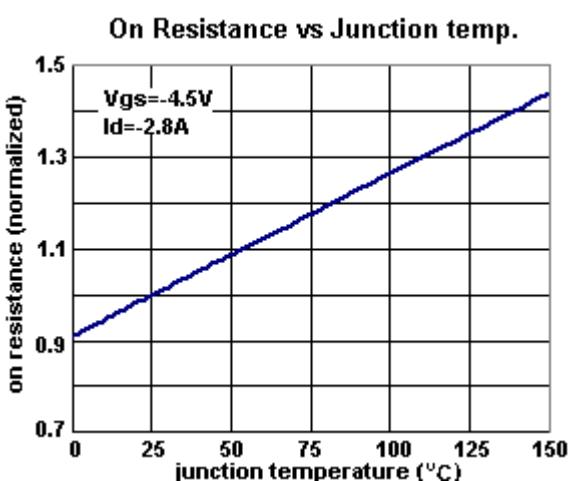
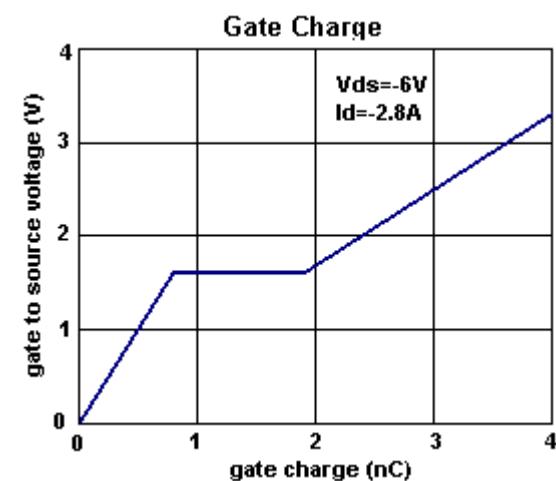
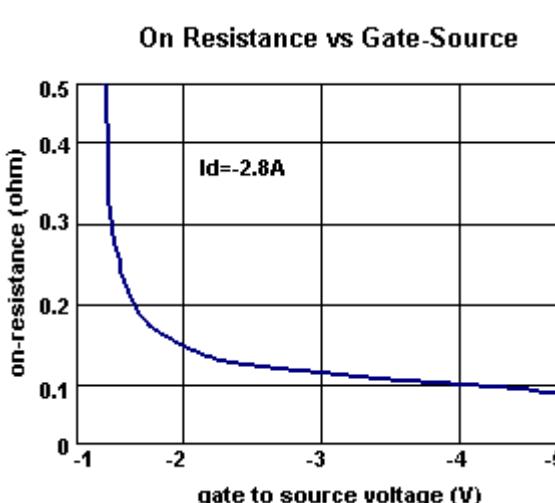
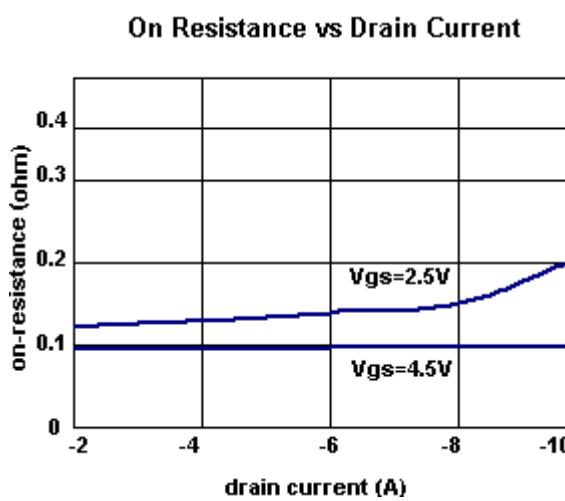
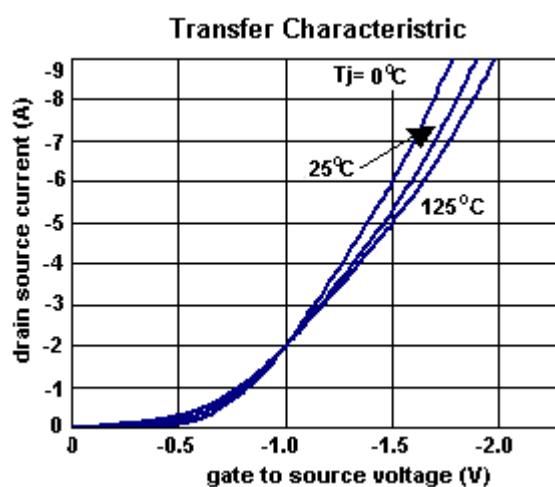
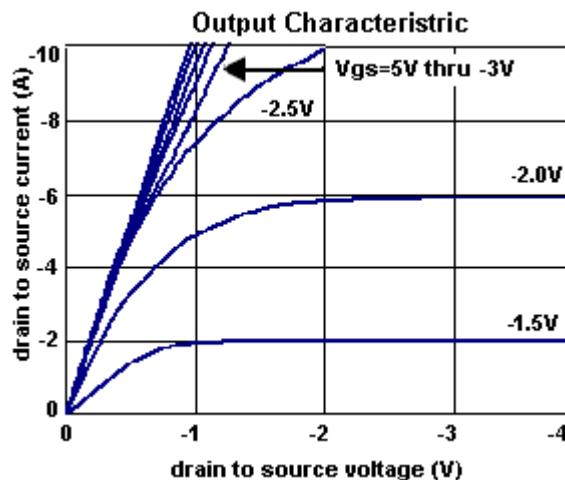


Switching Test Circuit



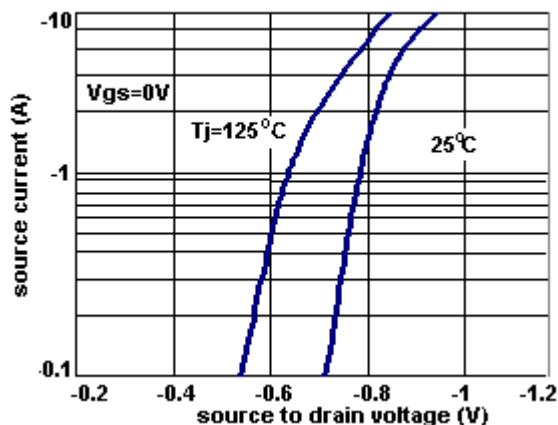
Switchin Waveforms

Typical Characteristics Curve ($T_a = 25^\circ\text{C}$ unless otherwise noted)

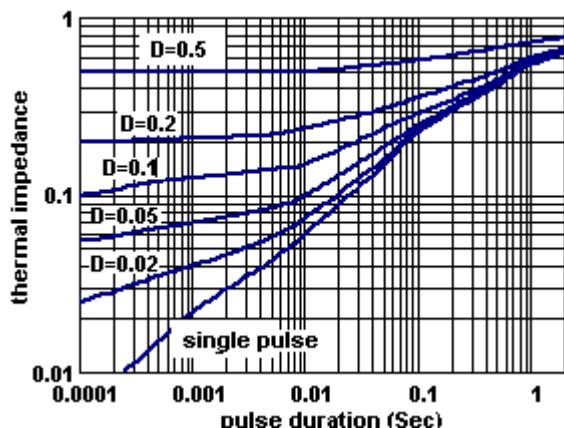


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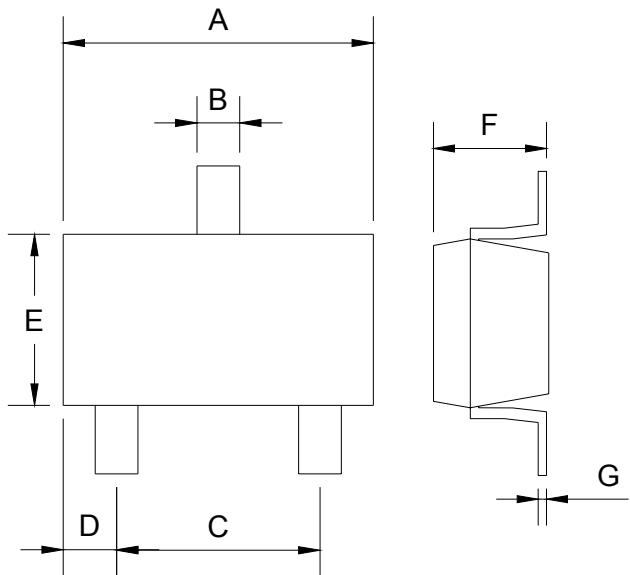
Source Drain Diode Forward Voltage



Transient Thermal Impedance



SOT-23 Mechanical Drawing



SOT-23 DIMENSION				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.88	2.91	0.113	0.115
B	0.39	0.42	0.015	0.017
C	1.78	2.03	0.070	0.080
D	0.51	0.61	0.020	0.024
E	1.59	1.66	0.063	0.065
F	1.04	1.08	0.041	0.043
G	0.07	0.09	0.003	0.004